

In re the Application of: Akira MATSUDA et al.

Group Art Unit: 1775

Application Number: 10/719,020

Examiner: Michael E. Lavilla

Filed: November 24, 2003

Confirmation Number: 9168

For:

PLATING BATH FOR FORMING THIN RESISTANCE LAYER,

METHOD OF FORMATION OF RESISTANCE LAYER, CONDUCTIVE BASE WITH RESISTANCE LAYER, AND CIRCUIT BOARD MATERIAL WITH RESISTANCE LAYER

Attorney Docket Number:

032130

Customer Number:

38834

AMENDMENT

Commissioner for Patents P. O. Box 1450 Alexandria, VA 22313-1450 June 27, 2007

Sir:

This paper is filed in response to the Office Action dated March 7, 2007, the response due date extended to July 7, 2007 by a one-month Extension of Time.

Amendments to the Claims begin on page 2 of this paper.

Remarks begin on page 4 of this paper.